

FPC

TE Internal #: 2-84952-8

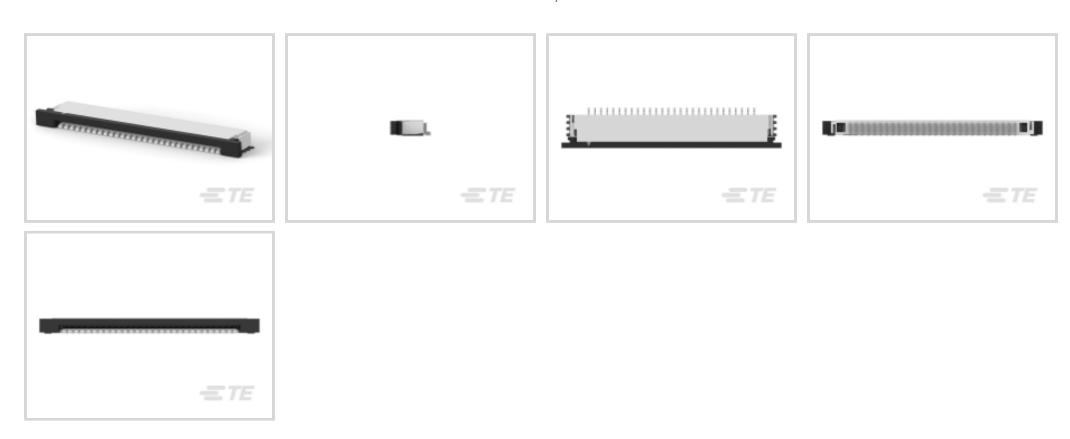
FPC Connectors, Flex-to-Board, 28 Position, .039 in [1 mm]

Centerline, Zero Insertion Force (ZIF), Right Angle, Surface Mount

View on TE.com >



Connectors > PCB Connectors > Wire-to-Board Connectors > FFC, FPC & Ribbon Connectors > FPC Connectors



Connector System: Flex-to-Board

Number of Positions: 28

Centerline (Pitch): 1 mm [.039 in]

Insertion Force Type: Zero Insertion Force (ZIF)

PCB Mount Orientation: Right Angle

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Receptacle
Connector Product Type	Connector Assembly
Connector System	Flex-to-Board
Insertion Force Type	Zero Insertion Force (ZIF)
FPC Actuator Type	Stuffer (Plunger Style)
Connector & Contact Terminates To	Flexible Printed Circuit (FPC)
Configuration Features	
Compatible With Wire & Cable Type	FFC, FPC
Number of Rows	1
Number of Positions	28
PCB Mount Orientation	Right Angle
Electrical Characteristics	

200 VAC

Operating Voltage



PCB Contact Termination Area Plating Material Thickness 2 µm[78.74 µin] Contact Layout Inline Contact Type Socket Contact Mating Area Plating Material Thickness 2 µm[78.74 µin] PCB Contact Termination Area Plating Material Finish Bright Contact Shape & Form Single Beam Contact Mating Area Plating Material Finish Bright PCB Contact Termination Area Plating Material Finish Bright PCB Contact Termination Area Plating Material Contact Base Material Phosphor Bronze Contact Mating Area Plating Material Contact Mating Area Plating Material Tin Contact Mating Area Plating Material Tin Contact Current Rating (Max) 1 A Termination Features Termination Method to Printed Circuit Board Surface Mount Mechanical Attachment Mating Alignment Without PCB Mount Alignment Without PCB Mount Retention With Connector Mounting Type Board Mount Housing Features Housing Material LCP (Liquid Crystal Polymer) Centerline (Pitch) 1 mm[.039 in]	Primary Product Color	Natural
Contact Layout Contact Type Socket Contact Mating Area Plating Material Thickness PCB Contact Termination Area Plating Material Finish Bright Contact Mating Area Plating Material Finish Bright Contact Mating Area Plating Material Finish Bright Contact Mating Area Plating Material Finish PCB Contact Termination Area Plating Material Tin Contact Base Material Contact Mating I location Bottom Contact Mating I location Contact Mating Area Plating Material Tin Contact Mating Area Plating Material Tin Contact Current Rating (Max) 1 A Termination Features Termination Method to Printed Circuit Board With Mechanical Attachment Mating Alignment PCB Mount Alignment PCB Mount Retention Connector Mounting Type Board Mount Housing Features Housing Material Centerline (Pitch) 1 mm(,039 in) Dimensions Connector Length Connector Height Connector Width 6.54 mm(,151 in) Connector Width	Contact Features	
Contact Layout Contact Type Socket Contact Mating Area Plating Material Thickness PCB Contact Termination Area Plating Material Finish Bright Contact Mating Area Plating Material Finish Bright Contact Mating Area Plating Material Finish Bright Contact Mating Area Plating Material Finish PCB Contact Termination Area Plating Material Tin Contact Base Material Contact Base Material Contact Mating I location Bottom Contact Mating I location Contact Mating Area Plating Material Tin Contact Current Rating (Max) 1 A Termination Features Termination Method to Printed Circuit Board Mechanical Attachment Mating Alignment PCB Mount Alignment PCB Mount Retention Connector Mounting Type Board Mount Housing Features Housing Material Centerline (Pitch) Dimensions Connector Length Connector Height Connector Width Connector Height Connector Width Connector Widt	PCB Contact Termination Area Plating Material Thickness	2 um[78.74 uin]
Contact Mating Area Plating Material Thickness 2 µm[78.74 µin] PCB Contact Termination Area Plating Material Finish Bright Contact Shape & Form Single Beam Contact Mating Area Plating Material Finish Bright PCB Contact Termination Area Plating Material Contact Mating Area Plating Material FCB Contact Termination Area Plating Material Contact Base Material Contact Base Material Contact Mating Location Contact Mating Area Plating Material Tin Contact Mating Area Plating Material Tin Contact Current Rating (Max) 1 A Termination Features Termination Method to Printed Circuit Board Mechanical Attachment Mating Alignment PCB Mount Alignment PCB Mount Retention Connector Mounting Type Board Mount Housing Features Housing Material Connector Mounting Type LCP (Liquid Crystal Polymer) Terminations Connector Length Connector Length Connector Height Connector Height Connector Width		
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PCB Contact Termination Area Plating Material Finish Single Beam Contact Shape & Form Single Beam Contact Mating Area Plating Material Finish Bright PCB Contact Termination Area Plating Material Tin Contact Base Material Phosphor Bronze Contact Mating Area Plating Material Tin Contact Mating Area Plating Material Tin Contact Mating Area Plating Material Tin Contact Current Rating (Max) 1 A Termination Features Termination Method to Printed Circuit Board Surface Mount Mechanical Attachment With PCB Mount Alignment Without PCB Mount Retention With Connector Mounting Type Board Mount Housing Features Housing Material LCP (Liquid Crystal Polymer) Centerline (Pitch) 1 mm[.039 in] Dimensions Connector Length 35.92 mm[.101 in] Connector Width 6.54 mm[.258 in]		2 μm[78.74 μin]
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Contact Mating Area Plating Material Contact Current Rating (Max) Termination Features Termination Method to Printed Circuit Board Mechanical Attachment Mating Alignment Mount Alignment PCB Mount Alignment With Connector Mounting Type Housing Features Housing Material Centerline (Pitch) Dimensions Connector Length Connector Height Connector Width Connector Width 2.56 mm[,101 in] Connector Width	Contact Base Material	Phosphor Bronze
Contact Current Rating (Max) Termination Features Termination Method to Printed Circuit Board Mechanical Attachment Mating Alignment PCB Mount Alignment PCB Mount Retention Connector Mounting Type Housing Features Housing Material Centerline (Pitch) Dimensions Connector Length Connector Height Connector Width 1 A A A A A B A A A A A A A A	Contact Mating Location	Bottom
Termination Features Termination Method to Printed Circuit Board Surface Mount Mechanical Attachment Mating Alignment Without PCB Mount Alignment Without PCB Mount Retention With Connector Mounting Type Board Mount Housing Features Housing Material LCP (Liquid Crystal Polymer) Centerline (Pitch) 1 mm[.039 in] Dimensions Connector Length 35.92 mm[1.414 in] Connector Height 2.56 mm[.101 in] Connector Width 6.54 mm[.258 in]	Contact Mating Area Plating Material	Tin
Termination Method to Printed Circuit Board Mechanical Attachment Mating Alignment Mount Alignment PCB Mount Alignment Without PCB Mount Retention With Connector Mounting Type Board Mount Housing Features Housing Material Centerline (Pitch) Dimensions Connector Length Connector Height Connector Width Surface Mount With Contest Mithout With LCP (Liquid Crystal Polymer) 1 mm[.039 in] Connector Length 35.92 mm[1.414 in] Connector Height Connector Width 6.54 mm[.258 in]	Contact Current Rating (Max)	1 A
Mechanical Attachment Mating Alignment PCB Mount Alignment PCB Mount Retention With Connector Mounting Type Board Mount Housing Features Housing Material Centerline (Pitch) Dimensions Connector Length Connector Height Connector Width Mating Alignment With With LCP (Liquid Crystal Polymer) 1 mm[.039 in] 2.56 mm[.101 in] Connector Width	Termination Features	
Mating Alignment PCB Mount Alignment Without PCB Mount Retention With Connector Mounting Type Board Mount Housing Features Housing Material Centerline (Pitch) Dimensions Connector Length Connector Height Connector Width With With LCP (Liquid Crystal Polymer) 1 mm[.039 in] 2.56 mm[.101 in] Connector Width 6.54 mm[.258 in]	Termination Method to Printed Circuit Board	Surface Mount
PCB Mount Alignment Without PCB Mount Retention With Connector Mounting Type Board Mount Housing Features Housing Material LCP (Liquid Crystal Polymer) Centerline (Pitch) 1 mm[.039 in] Dimensions Connector Length 35.92 mm[1.414 in] Connector Height 2.56 mm[.101 in] Connector Width 6.54 mm[.258 in]	Mechanical Attachment	
PCB Mount Alignment Without PCB Mount Retention With Connector Mounting Type Board Mount Housing Features Housing Material LCP (Liquid Crystal Polymer) Centerline (Pitch) 1 mm[.039 in] Dimensions Connector Length 35.92 mm[1.414 in] Connector Height 2.56 mm[.101 in] Connector Width 6.54 mm[.258 in]	Mating Alignment	With
Connector Mounting Type Housing Features Housing Material Centerline (Pitch) Dimensions Connector Length Connector Height Connector Width Board Mount LCP (Liquid Crystal Polymer) 1 mm[.039 in] 5.92 mm[1.414 in] 2.56 mm[.101 in] 6.54 mm[.258 in]	PCB Mount Alignment	Without
Housing Features Housing Material Centerline (Pitch) Dimensions Connector Length Connector Height Connector Width LCP (Liquid Crystal Polymer) 1 mm[.039 in] 2.56 mm[1.414 in] 6.54 mm[.258 in]	PCB Mount Retention	With
Housing Material Centerline (Pitch) Dimensions Connector Length Connector Height Connector Width LCP (Liquid Crystal Polymer) 1 mm[.039 in] 35.92 mm[1.414 in] 2.56 mm[.101 in] 6.54 mm[.258 in]	Connector Mounting Type	Board Mount
Centerline (Pitch) Dimensions Connector Length Connector Height Connector Width 1 mm[.039 in] 35.92 mm[1.414 in] 2.56 mm[.101 in] 6.54 mm[.258 in]	Housing Features	
DimensionsConnector Length35.92 mm[1.414 in]Connector Height2.56 mm[.101 in]Connector Width6.54 mm[.258 in]	Housing Material	LCP (Liquid Crystal Polymer)
Connector Length 35.92 mm[1.414 in] Connector Height 2.56 mm[.101 in] Connector Width 6.54 mm[.258 in]	Centerline (Pitch)	1 mm[.039 in]
Connector Height Connector Width 2.56 mm[.101 in] 6.54 mm[.258 in]	Dimensions	
Connector Width 6.54 mm[.258 in]	Connector Length	35.92 mm[1.414 in]
	Connector Height	2.56 mm[.101 in]
Accepts Flex Cable Thickness .3 mm[.012 in]	Connector Width	6.54 mm[.258 in]
	Accepts Flex Cable Thickness	.3 mm[.012 in]
Usage Conditions	Usage Conditions	
Operating Temperature Range -40 – 85 °C[-40 – 185 °F]	Operating Temperature Range	-40 - 85 °C[-40 - 185 °F]
Operation/Application	Operation/Application	



Circuit Application	Signal
Identification Marking	
Circuit Identification Feature	With
Packaging Features	
Packaging Features Packaging Quantity	1200

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts









Customers Also Bought



















Documents

Product Drawings

1MM FPC HORZ.BOTTOM CONT.ASSY 28P

English

CAD Files

Customer View Model ENG_CVM_CVM_2-84952-8_A.2d_dxf.zip

English

3D PDF



3D

Customer View Model

ENG_CVM_CVM_2-84952-8_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2-84952-8_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

1-1773959-6-flexible-printed-circuit-con

English

1-1773959-7-FPC-Connectors-CN

FPC Connector Family

English

5-1773461-0_Standard_FPC_Connector_Quick_Reference_Guide

English

Product Specifications

Product Specification

English

Agency Approvals

UL Report

English